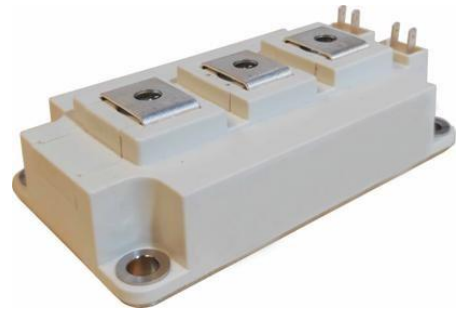


Electrical Features

- Trench/Fieldstop IGBT
- Half-bridge
- Standard package
- Including anti-parallel FWD



Typical Applications

- UPS System
- Motor Drivers
- Welding Machine
- High Frequency Switching Application

IGBT, Inverter

Maximum Rated Values							
Symbol	Item	Conditions	Rating			Unit	
IGBT							
V_{CES}	Collector-emitter voltage	$T_{vj}=25^{\circ}C$	1200			V	
V_{GES}	Gate-emitter voltage	-	± 20			V	
I_C	Collector current,DC	$T_C=100^{\circ}C, T_{vj}=175^{\circ}C$	150			A	
I_{CRM}	Repetitive peak collector current	$t_p=1ms$	300			A	
P_{tot}	Total power dissipation	$T_C=25^{\circ}C, T_{vj}=175^{\circ}C$	937			W	
Characteristics Values							
Symbol	Item	Conditions	Values			Unit	
			Min.	Typ.	Max.		
I_{CES}	Collector-emitter cut-off current	$V_{CE}=1200V, V_{GE}=0V, T_{vj}=25^{\circ}C$	-	-	1	mA	
I_{GES}	Gate leakage current	$V_{CE}=0V, V_{GE}=20V, T_{vj}=25^{\circ}C$	-	-	250	nA	
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C=5.7mA, V_{CE}=V_{GE}, T_{vj}=25^{\circ}C$	5	5.8	7	V	
V_{CEsat}	Collector-emitter saturation voltage	$I_C=150A$ $V_{GE}=15V$	$T_{vj}=25^{\circ}C$	-	1.81		2.3
			$T_{vj}=125^{\circ}C$	-	2.16		-
			$T_{vj}=150^{\circ}C$	-	2.26	-	
C_{ies}	Input capacitance	$V_{CE}=25V, V_{GE}=0V$	-	9.7	-	nF	
C_{res}	Reverse transfer capacitance	$f=1MHz, T_{vj}=25^{\circ}C$	-	0.3	-		
Q_G	Gate charge	$V_{CC}=600V, I_C=150A, V_{GE}=15V$	-	1.2	-	μC	

$t_{d(on)}$	Turn-on delay time	$V_{CC}=600V$ $I_C=150A$ $V_{GE}=\pm 15V$ $R_{G(on)}=10\Omega$ $R_{G(off)}=10\Omega$ Inductive load	$T_{vj}=25^\circ C$	-	81.6	-	ns	
			$T_{vj}=125^\circ C$	-	93.2	-		
			$T_{vj}=150^\circ C$	-	95.4	-		
t_r	Rise time		$T_{vj}=25^\circ C$	-	38.5	-		
			$T_{vj}=125^\circ C$	-	42.1	-		
			$T_{vj}=150^\circ C$	-	43.2	-		
$t_{d(off)}$	Turn-off delay time		$T_{vj}=25^\circ C$	-	243.2	-		
			$T_{vj}=125^\circ C$	-	265.6	-		
			$T_{vj}=150^\circ C$	-	272.0	-		
t_f	Fall time	$T_{vj}=25^\circ C$	-	164.8	-			
		$T_{vj}=125^\circ C$	-	192.0	-			
		$T_{vj}=150^\circ C$	-	211.2	-			
E_{on}	Turn-on energy (per pulse)	$V_{CC}=600V, I_C=150A$ $V_{GE}=\pm 15V, R_{G(on)}=10\Omega$ $di/dt=8780A/\mu s(T_{vj}=150^\circ C)$	$T_{vj}=25^\circ C$	-	9.40	-	mJ	
			$T_{vj}=125^\circ C$	-	13.16	-		
			$T_{vj}=150^\circ C$	-	14.71	-		
E_{off}	Turn-off energy (per pulse)		$T_{vj}=25^\circ C$	-	7.39	-		
			$T_{vj}=125^\circ C$	-	9.81	-		
			$T_{vj}=150^\circ C$	-	10.31	-		
R_{thJC}	Thermal resistance, junction to case		per IGBT	-	-	0.16		K/W
R_{thCH}	Thermal resistance, case to heatsink		per IGBT/ $\lambda_{grease}=1W/(m \cdot K)$	-	0.03	-		K/W
T_{vjop}	Temperature under switching conditions			-40		150		$^\circ C$
Diode, Inverter								
Maximum Rated Values								
Symbol	Item	Conditions		Rating		Unit		
V_{RRM}	Repetitive peak reverse voltage	$T_{vj}=25^\circ C$		1200		V		
I_F	Forward current, DC			60		A		
I_{FRM}	Repetitive peak forward current	$t_p=1ms$		120		A		
Characteristic Values								
V_F	Continuous forward voltage	$I_F=60A$ $V_{GE}=0V$	$T_{vj}=25^\circ C$	-	1.86	2.3	V	
			$T_{vj}=125^\circ C$	-	1.57	-		
			$T_{vj}=150^\circ C$	-	1.48	-		
I_{RM}	Peak reverse recovery current		$T_{vj}=25^\circ C$	-	164	-	A	
			$T_{vj}=125^\circ C$	-	180	-		
			$T_{vj}=150^\circ C$	-	192	-		
t_{rr}	Reverse recovery time		$T_{vj}=25^\circ C$	-	68.7	-	ns	
			$T_{vj}=125^\circ C$	-	114.9	-		
			$T_{vj}=150^\circ C$	-	138.6	-		
Q_r	Recovered charge	$V_R=600V$ $I_F=150A$ $V_{GE}=-15V$ $-di_F/dt=5200A/\mu s$ $(T_{vj}=150^\circ C)$	$T_{vj}=25^\circ C$	-	6.0	-	μC	
			$T_{vj}=125^\circ C$	-	20.6	-		
			$T_{vj}=150^\circ C$	-	24.7	-		
E_{rec}	Reverse recovery energy		$T_{vj}=25^\circ C$	-	2.69	-	mJ	
			$T_{vj}=125^\circ C$	-	11.86	-		
			$T_{vj}=150^\circ C$	-	14.16	-		

R_{thJC}	Thermal resistance, junction to case	per diode	-	-	0.3	K/W
R_{thCH}	Thermal resistance, case to heatsink	per diode/ $\lambda_{grease}=1W/(m \cdot K)$	-	0.06	-	K/W
T_{vjop}	Temperature under switching conditions		-40		150	°C

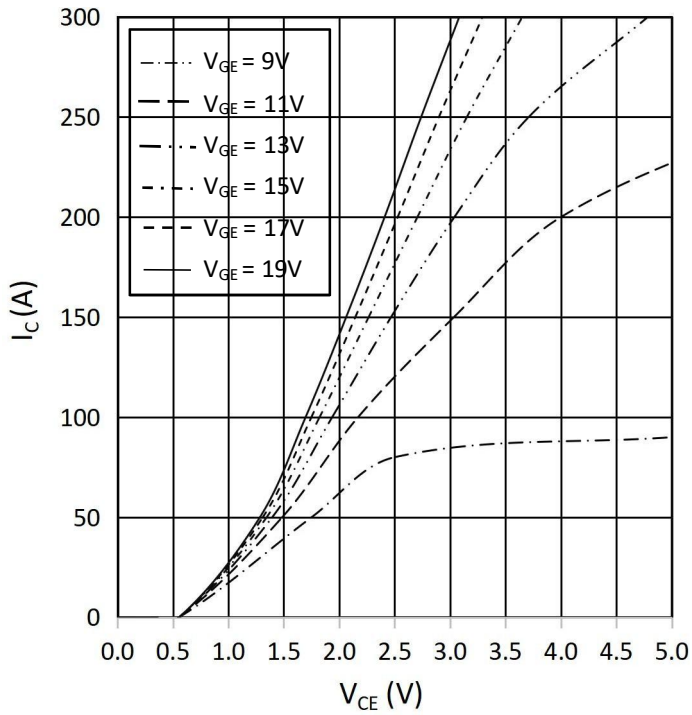
Module

Symbol	Item	Conditions	Rating			Unit
V_{ISOL}	Isolation voltage	Terminals to baseplate, RMS, $f=50Hz, t=1min$	2500			V
-	Material of module baseplate	-	Cu			-
-	Internal isolation	Basic insulation(class 1, IEC 61140)	Al_2O_3			-
T_{stg}	Storage temperature	-	-40~125			°C
Symbol	Item	Conditions	Values			Unit
			Min.	Typ.	Max.	
M	Mounting torque for module mounting	Screw M6	3.0	-	6.0	Nm
	Terminal connection torque	Screw M6	2.5	-	5.0	Nm
ds	Creepage distance	Terminal to terminal	-	23	-	mm
		Terminal to base plate	-	29	-	
da	Clearance	Terminal to terminal	-	11	-	mm
		Terminal to base plate	-	23	-	
m	Weight	-	-	315	-	g

output characteristic IGBT, Inverter (typical)

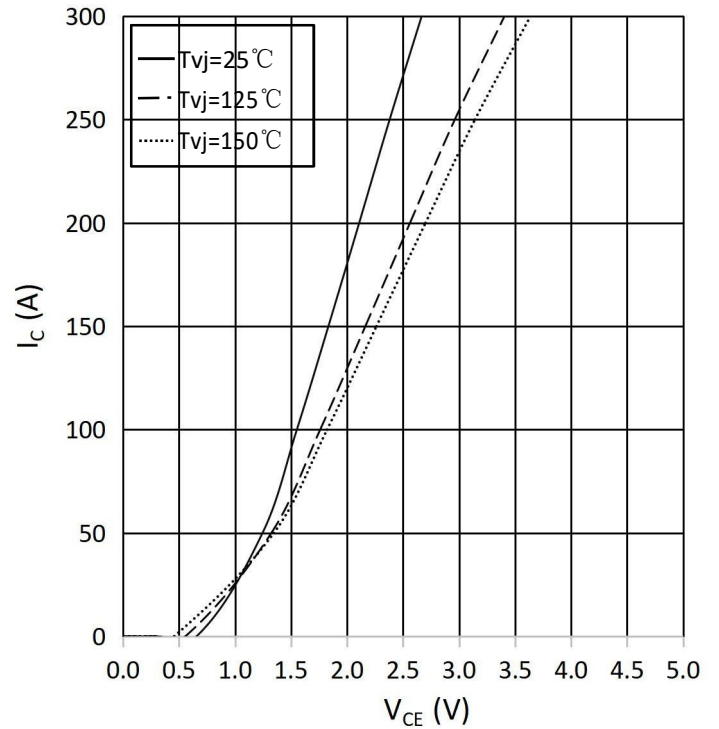
$I_C = f(V_{CE})$

$T_{vj} = 150^{\circ}\text{C}$


output characteristic IGBT, Inverter (typical)

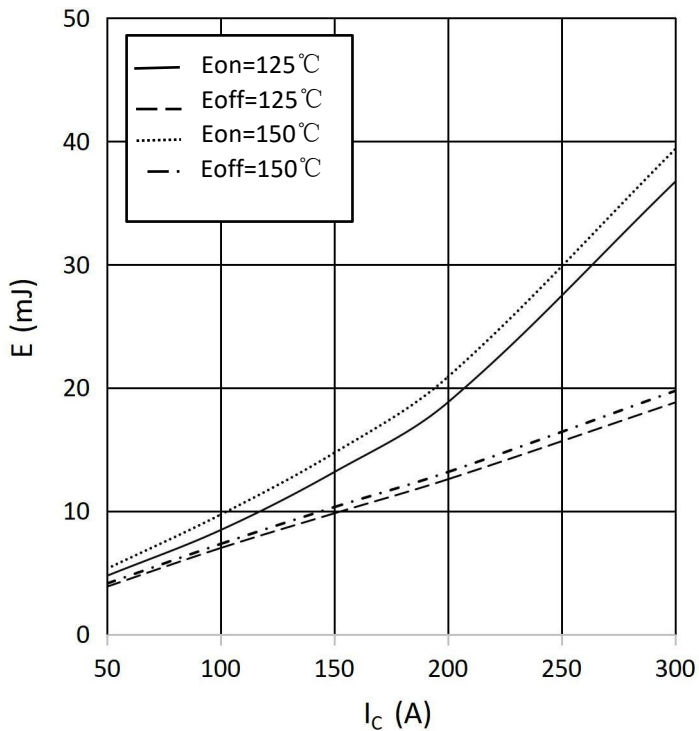
$I_C = f(V_{CE})$

$V_{GE} = 15\text{ V}$


switching losses IGBT, Inverter (typical)

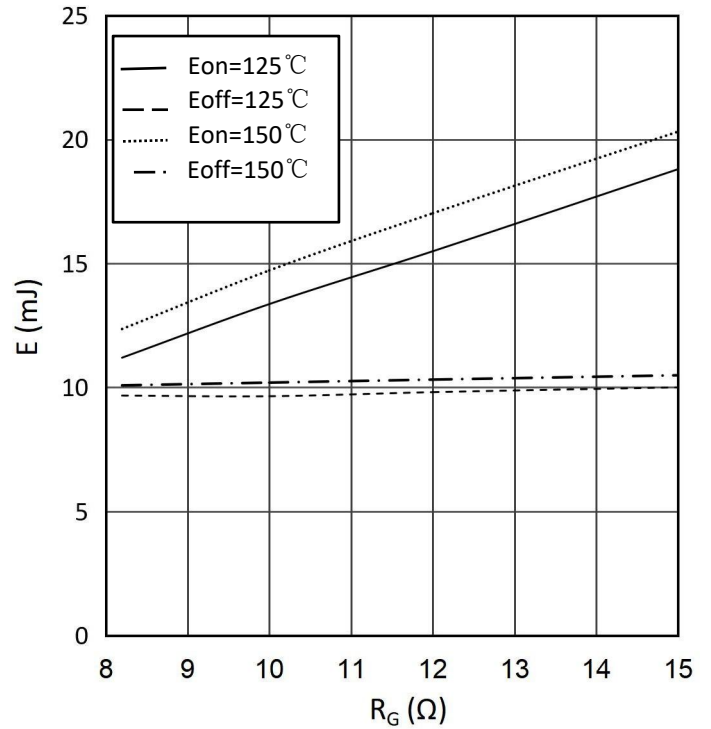
$E_{on} = f(I_C), E_{off} = f(I_C)$

$V_{GE} = \pm 15\text{V}, R_{Gon} = 10\Omega, R_{Goff} = 10\Omega, V_{CE} = 600\text{V}$


switching losses IGBT, Inverter (typical)

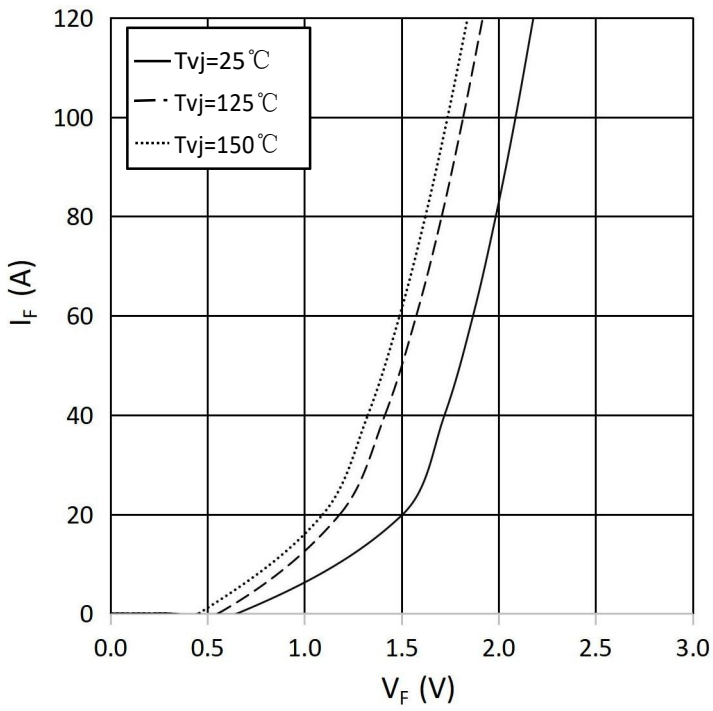
$E_{on} = f(R_G), E_{off} = f(R_G)$

$V_{GE} = \pm 15\text{V}, I_C = 150\text{A}, V_{CE} = 600\text{V}$



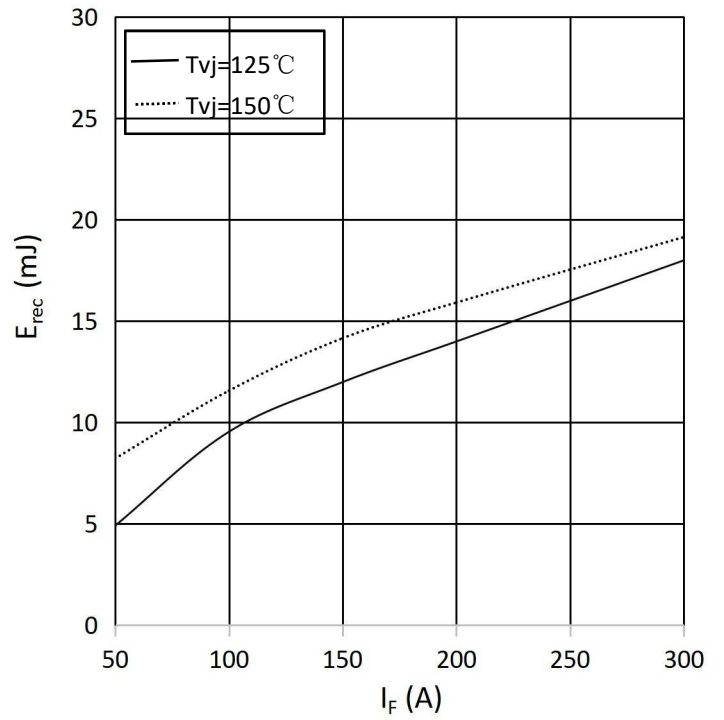
forward characteristic of Diode, Inverter (typical)

$$I_F = f(V_F)$$

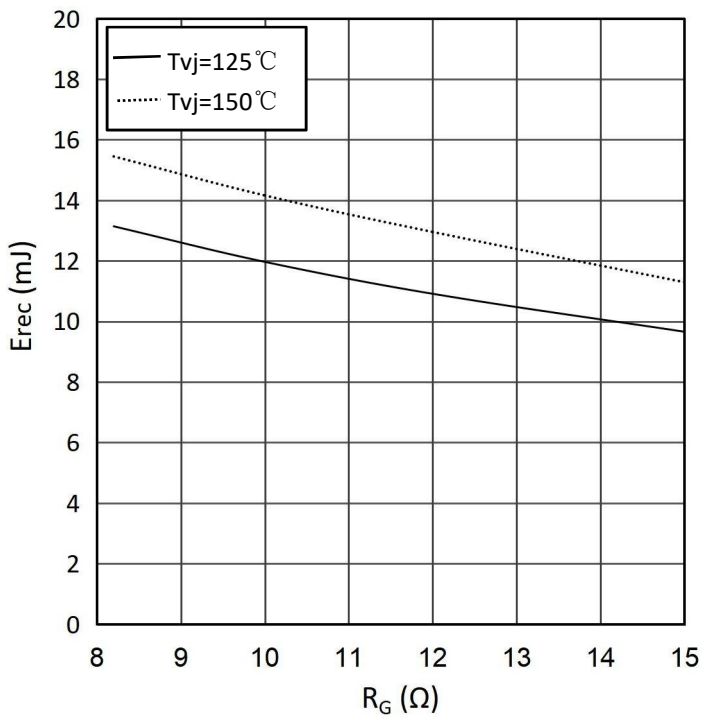

switching losses Diode, Inverter (typical)

$$E_{rec} = f(I_F)$$

$$R_{Gon}=10\Omega, V_{CE}=600V$$

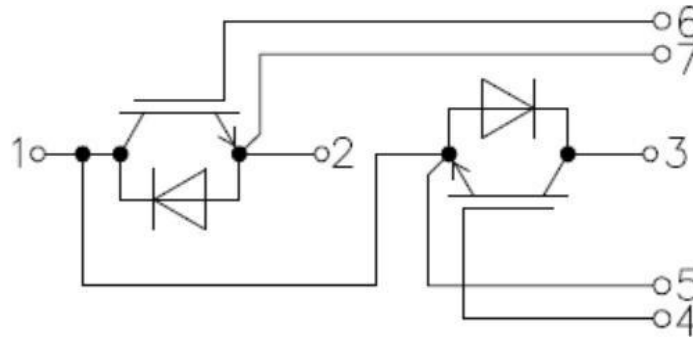

switching losses Diode, Inverter (typical)

$$E_{rec} = f(R_G)$$

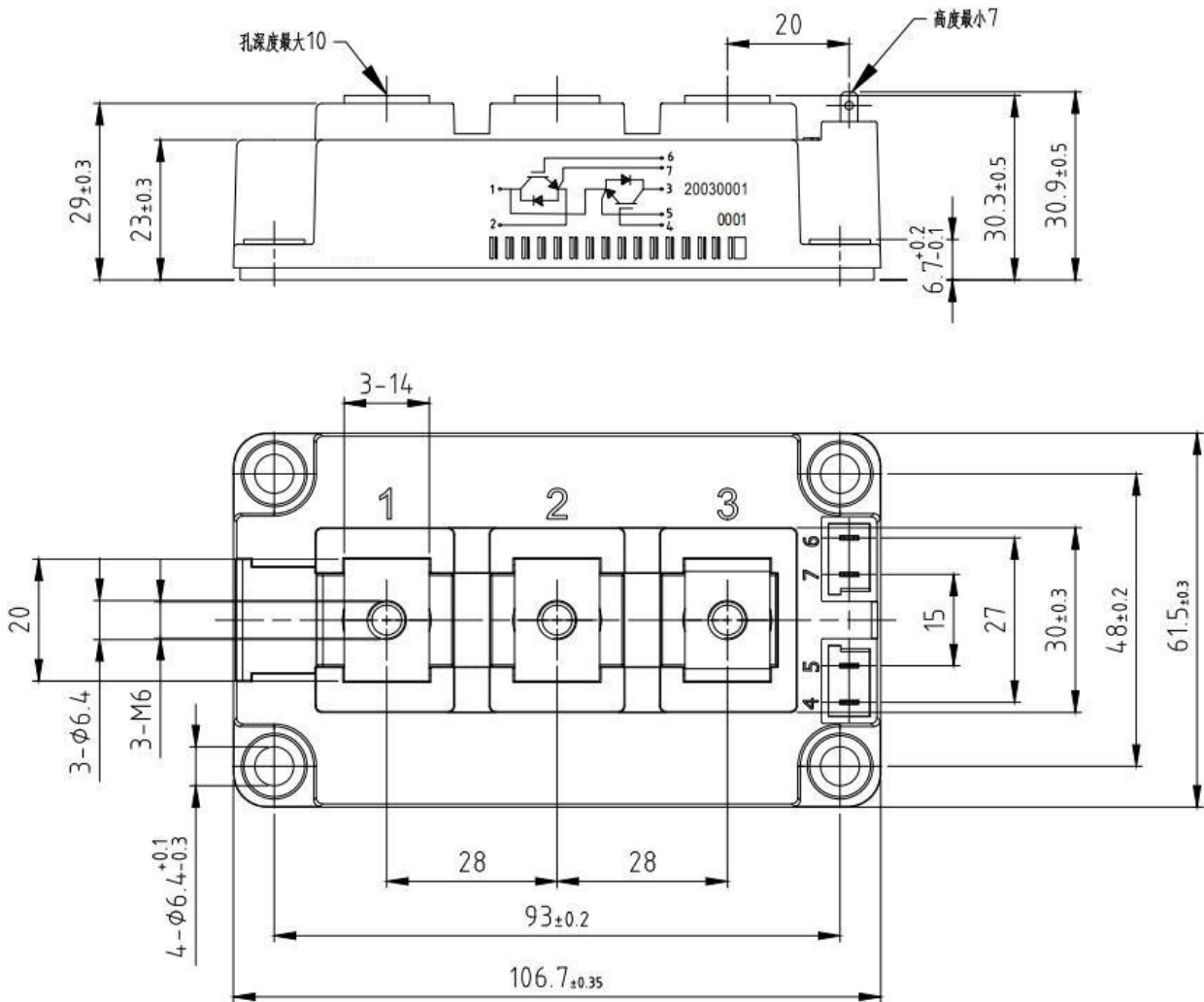


$$I_F=150A, V_{CE}=600V$$

Circuit diagram headline



Package outlines (Unit: mm)



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